
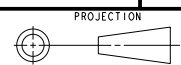




REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
1	SEE SHEET 1			

PACKAGE DIMENSIONS (MICROMETERS)					
X1 DESIGNATOR	X1 PACKAGE WIDTH $\pm 30 \mu\text{m}$	X2 DESIGNATOR	X2 PACKAGE LENGTH $\pm 30 \mu\text{m}$	X3 DESIGNATOR	X3 PACKAGE HEIGHT $\pm 75 \mu\text{m}$
Z	1945	Z	2174	A	600
1	1970	1	2199		
A	1996	A	2225		
B	2022	B	2250		
C	2047	C	2276		
D	2073	D	2301		
E	2098	E	2327		
F	2123	F	2352		
G	2149	G	2377		
H	2174	H	2403		
J	2200	J	2428		
K	2225	K	2454		
L	2250	L	2479		
M	2276	M	2504		
N	2301	N	2530		
P	2327	P	2555		
Q	2352	Q	2581		
R	2377	R	2606		
S	2403	S	2631		
T	2428	T	2657		
U	2454	U	2682		
V	2479	V	2708		
		W	2733		
		X	2758		
		Y	2784		
		2	2809		
		3	2835		
		4	2860		
		5	2885		
		6	2911		
		7	2936		
		8	2962		
		9	2987		

APPROVALS		DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN	<b>MARTA SUCHY</b>	02/26/2002	
DFTG. CHK.	THANH LEQUANG	05/29/2007	
ENGR. CHK.	JEFF SCHAEFER	05/29/2007	
			THIN MICRO SMD, 14 BUMP(LARGE), PERIPHERAL, 0.5mm PITCH
SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-TLP14XXX	D
FORMERLY: N/A			SHEET 2 of 2